

NOTES: UNLESS OTHERWISE SPECIFIED

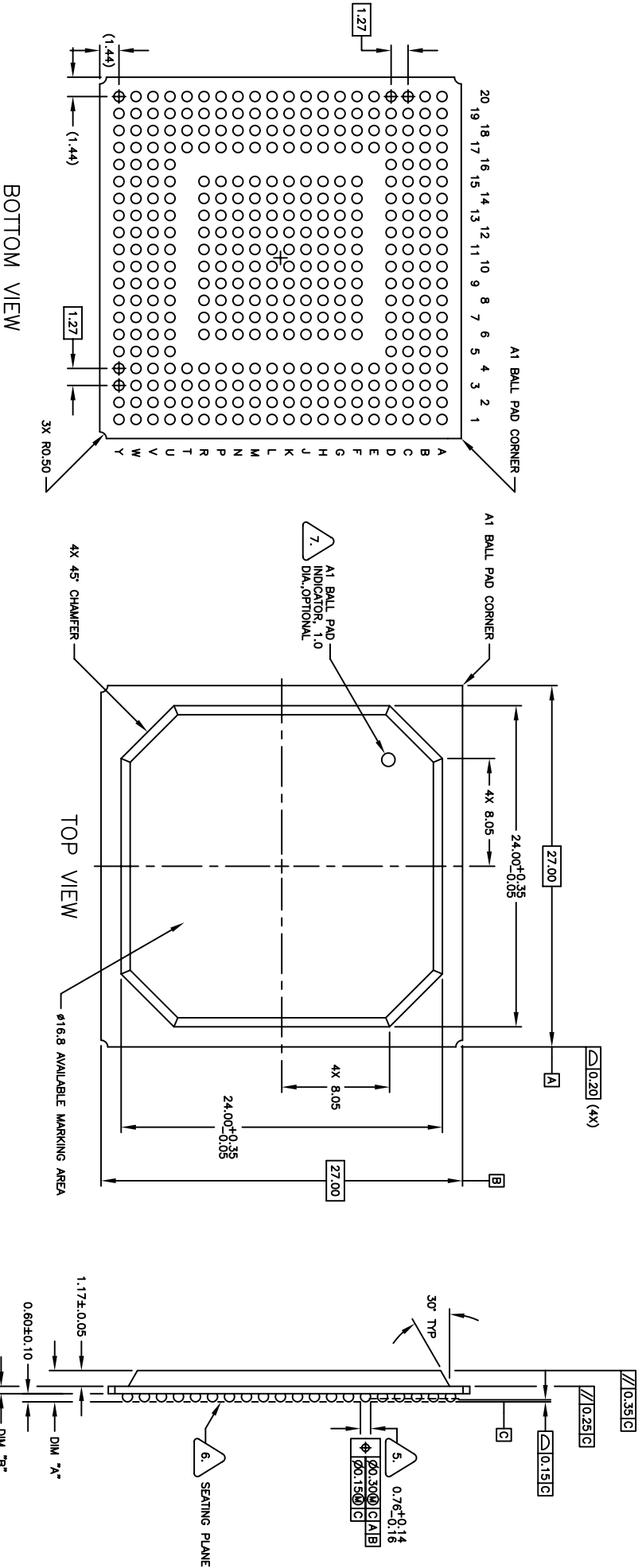
1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.
2. THE BASIC SOLDER BALL GRID PITCH IS 1.27mm.
3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 20 X 20.
4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 400.

5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.

6. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



7. A1 BALL PAD CORNER I.D. FOR PLATE MOLD: TO BE MARKED BY INK. AUTO MOLD: DIMPLE TO BE FORMED BY MOLD CAP. REFERENCE SPECIFICATIONS: A. THIS DRAWING CONFORMS TO THE JEDEC REGISTERED OUTLINE MS-034/A VARIATION BAL-2.



356 SOLDER BALLS

Drawing #: V356.27x27

Rev: 0

Date: 2/28/06

Units: mm



PACKAGE OUTLINE DRAWING- 356 PBGA  
27 x 27 mm x 1.17 mm MOLD CAP,  
1.27 mm PITCH SUBSTRATE

NO. LAYERS	DIM "A"	DIM "B"	STANDARD	NOTES
4	2.38±0.21	0.61±0.06	STANDARD	
PBGA THICKNESS SCHEDULE				